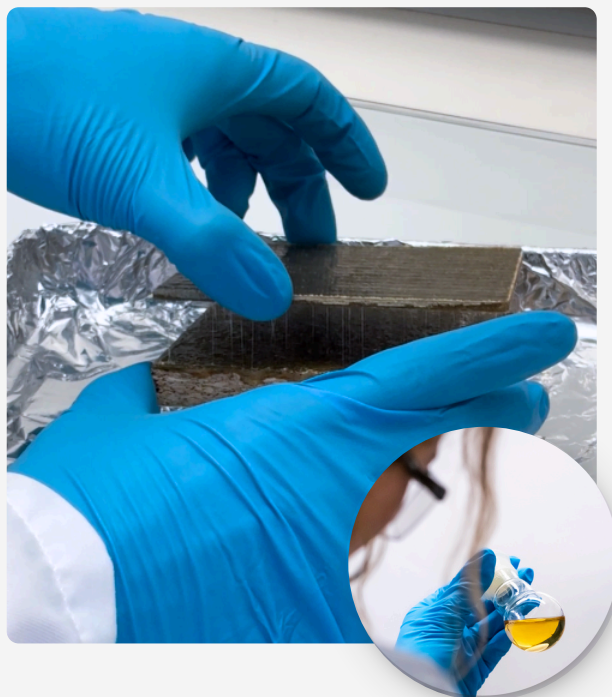


Discover a breakthrough in bonding technology - Our reversible adhesive delivers robust, long-lasting adhesion across a wide range of materials, while offering the unique ability to detach components by simple heat application when needed.

INTRODUCTION

Within the context of a greener and circular economy, reversible adhesive able to debond-on-demand (DoD) is emerging since it extends product lifespan and recycling. Reversible DoD adhesive allows substrates to bond together, then thanks to an external stimulus, substrates can be debonded for reuse or repair. According to the debonding stimulus targeted, various technologies can be used such as thermo-expandable particles, photo-reversible chemical groups, conductive particles or covalent-adaptable networks (CAN). At Specific Polymers, we use our expertise in polymer chemistry to develop innovative reversible adhesives based on CAN technology. This technology enables easy and safe debonding by thermal actuation.



SP-3607_V1 is a partially biobased 2K **reversible adhesive** specifically designed to provide adhesion across a wide range of substrates and operating temperatures (up to 70°C). It enables **easy debonding** when heated at **110°C** using standard heating tools. Its performance has been validated on materials including plastics, composites, wood and metal. Furthermore, the **low viscosity** of SP3607_V1 ensures superior **wetting** as well as smooth and efficient application.

KEY FEATURES

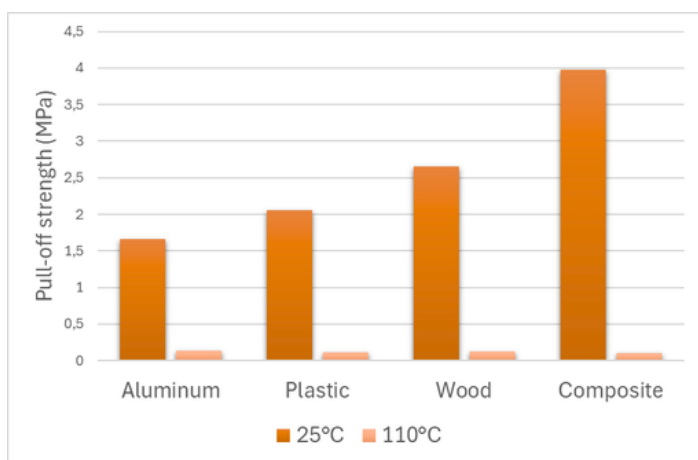
- 1. Debonding-on-demand by thermal activation:** Enables durable adhesion with the ability to easily debond components. No harsh chemicals required.
- 2. Wide substrate compatibility:** Proven performance on plastics, composites, wood and metals.
- 3. Low viscosity for easy application:** Ensures excellent substrate wetting and smooth application.
- 4. Extend your product lifespan:** activate the debonding of the adhesive and change only the part to replace.

MAIN CHARACTERISTICS

CRUDE FORMULATION

VISCOSITY (25°C)	Part A	150 (±50) cP
	Part B	760 (±130) cP
SOLID CONTENT		79 - 85 wt%

ADHESION STRENGTH



THERMAL PROPERTIES

GLASS TRANSITION TEMPERATURE T_g	~20°C
CURING TEMPERATURE	From 50 to 80°C
DEBONDING TEMPERATURE	From 110 to 140°C

The following values provide indicative adhesion performance at room temperature (bonding conditions) and at 110°C (debonding conditions). Results may vary depending on substrate type, surface preparation, and processing parameters.

PROCESSING PARAMETERS

MIX RATIO (BY WEIGHT)

COMPONENT A (BASE)	100
COMPONENT B (HARDENER)	76

INSTRUCTIONS FOR USE

Before use, mix the SP3607_V1-PartA by stirring manually. Add 76 parts SP3607_V1-PartB to 100 parts of SP3607_V1-PartA (by weight). Mix the formulation by stirring manually until a homogeneous mixture is obtained.

SURFACE PREPARATION AND PRE-TREATMENT

Before application, ensure that both substrates are dust-free and degreased.

APPLICATION METHOD

The formulation can be applied by brush or spray-coater.

RECOMMENDED CURING CYCLE

Typical curing cycle involves: 1 h at room temperature + 30 min at 55°C + 2h at 70°C.

The curing conditions can be tuned to fit specific requirements.